

L Number	Hits	Search Text	DB	Time stamp
1	40537	mold near2 (upper lower)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 09:35
2	7365	(mold near2 (upper lower)) and (chip die wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 09:37
3	4354	((mold near2 (upper lower)) and (chip die wafer)) and (methor process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 09:39
4	5701	((mold near2 (upper lower)) and (chip die wafer)) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 09:39
5	173	((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 09:45
6	0	((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)) and ((releasable released releasing) near (film layer tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 11:07
7	12	((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)) and ((releasable released release releasing) near (film layer tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 14:36
8	0	20020017738.URPN.	USPAT	2003/03/27 12:20
9	55	((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)) and ((releasable released release releasing) near (film layer tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 14:35
10	43	(((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)) and ((releasable released release releasing)) not (((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)) and ((releasable released release releasing) near (film layer tape)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 12:24
11	98	5450283.URPN.	USPAT	2003/03/27 14:35
12	759	((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (bump ball)	USPAT	2003/03/27 14:35
13	671	((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (bump ball) not (((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)))	USPAT	2003/03/27 14:35
14	275	(((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (bump ball) not (((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip))) and ((releasable released release releasing))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 14:36
15	10	(((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (bump ball) not (((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip))) and ((releasable released release releasing) near1 (film layer tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 14:43
16	2	6019588.URPN.	USPAT	2003/03/27 14:41

17	16	("4044984" "4236689" "4332537" "4442056" "4470786" "4697784" "4779835" "5059105" "5118271" "5218759" "5429488" "5484274" "5626886" "5639695" "5693572" "5779958").PN.	USPAT	2003/03/27 14:41
18	265	((((((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (bump ball)) not (((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)))) and (releasable released release releasing) not (((((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (bump ball)) not (((mold near2 (upper lower)) and (chip die wafer)) and (method process)) and (flipchip (flip adj chip)))) and ((releasable released release releasing) near1 (film layer tape)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/03/27 14:43